

Single P-Channel MOSFET

■ DESCRIPTION

SMC3407S is the P-Channel trench technology devices are well suited for high efficiency fast switching applications, low in-line power loss needed in small outline surface mount package.

■ PART NUMBER INFORMATION

SMC 3407 S - TR G

a b c d e

a : Company name.
 b : Product Serial number.
 c : Package code S: SOT-23L
 d : Handling code TR: Tape&Reel
 e : Green produce code G: RoHS Compliant

■ FEATURES

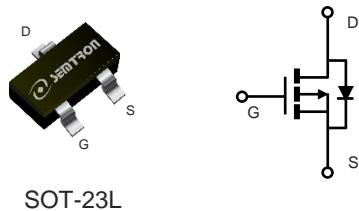
$V_{DS}=-30V$, $I_D=-4.5A$

$R_{DS(ON)}=43m\Omega$ (Typ.)@ $V_{GS}=-10V$

$R_{DS(ON)}=56m\Omega$ (Typ.)@ $V_{GS}=-4.5V$

■ APPLICATIONS

- ◆ Portable Equipment
- ◆ Power Management
- ◆ Load Switch



SOT-23L

■ ABSOLUTE MAXIMUM RATINGS ($T_A=25^\circ C$ Unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DSS}	Drain-Source Voltage	-30	V
V_{GSS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current ^A	$T_A=25^\circ C$	-4.5
		$T_A=70^\circ C$	-3.6
I_{DM}	Pulsed Drain Current ^B	-18	A
P_D	Power Dissipation ^A	$T_A=25^\circ C$	1.6
		$T_A=70^\circ C$	1
T_J	Operation Junction Temperature	-55/150	$^\circ C$
T_{STG}	Storage Temperature Range	-55/150	$^\circ C$

■ THERMAL RESISTANCE

Symbol	Parameter	Typ	Max	Units
$R_{\theta JA}$	Thermal Resistance Junction to Ambient ^A	$t \leq 10s$	80	$^\circ C/W$
	Thermal Resistance Junction to Ambient ^{AC}	Steady-State	120	

ELECTRICAL CHARACTERISTICS($T_A=25^\circ\text{C}$ Unless otherwise noted)

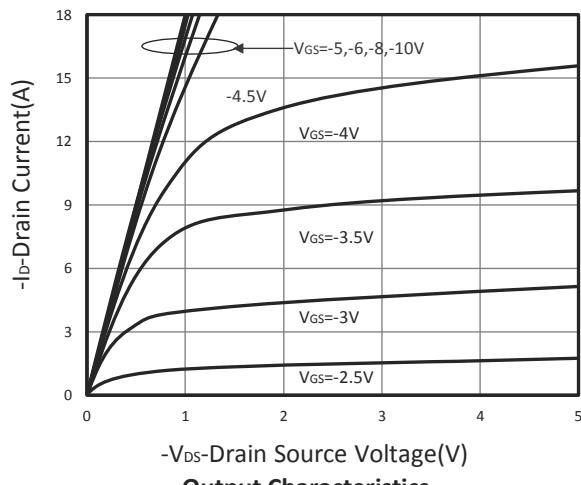
Symbol	Parameter	Condition	Min	Typ	Max	Unit	
Static Parameters							
BV_{DSS}	Drain-Source Breakdown Voltage	$\text{V}_{\text{GS}}=0\text{V}, \text{I}_D=-250\mu\text{A}$	-30			V	
$\text{V}_{\text{GS(th)}}$	Gate Threshold Voltage	$\text{V}_{\text{DS}}=\text{V}_{\text{GS}}, \text{I}_D=-250\mu\text{A}$	-1	-1.5	-2	V	
I_{GSS}	Gate Leakage Current	$\text{V}_{\text{DS}}=0\text{V}, \text{V}_{\text{GS}}=\pm20\text{V}$			±100	nA	
I_{DSS}	Zero Gate Voltage Drain Current	$\text{V}_{\text{DS}}=-30\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{T}_J=25^\circ\text{C}$			-1	μA	
		$\text{V}_{\text{DS}}=-24\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{T}_J=75^\circ\text{C}$			-10		
$\text{R}_{\text{DS(ON)}}$	Drain-source On-Resistance ^D	$\text{V}_{\text{GS}}=-10\text{V}, \text{I}_D=-4.5\text{A}$		43	48	$\text{m}\Omega$	
		$\text{V}_{\text{GS}}=-4.5\text{V}, \text{I}_D=-3.2\text{A}$		56	66		
G_{fs}	Forward Transconductance	$\text{V}_{\text{DS}}=-10\text{V}, \text{I}_D=-4.5\text{A}$		12		S	
Diode Characteristics							
V_{SD}	Diode Forward Voltage ^D	$\text{I}_S=-1\text{A}, \text{V}_{\text{GS}}=0\text{V}$			-1	V	
I_S	Diode Continuous Forward Current				-4.5	A	
t_{rr}	Revese Recovery Time	$\text{I}_S=-4.5\text{A}, \frac{d\text{I}}{dt}=100\text{A}/\mu\text{s}$		8.1		ns	
Q_{rr}	Revese Recovery Charg			2.7		nC	
Dynamic and Switching Parameters ^E							
Q_g	Total Gate Charge	$\text{V}_{\text{DS}}=-15\text{V}, \text{V}_{\text{GS}}=-10\text{V}$ $\text{I}_D=-4.5\text{A}$		13.9	19.5	nC	
Q_g	Total Gate Charge(4.5V)			6.8	9.5		
Q_{gs}	Gate-Source Charge			2.9	4.1		
Q_{gd}	Gate-Drain Charge			3.5	4.9		
C_{iss}	Input Capacitance	$\text{V}_{\text{DS}}=-15\text{V}, \text{V}_{\text{GS}}=0\text{V}, \text{f}=1\text{MHz}$		750		pF	
C_{oss}	Output Capacitance			95			
C_{rss}	Reverse Transfer Capacitance			82			
$\text{t}_{\text{d(on)}}$	Turn-On Time	$\text{V}_{\text{DD}}=-15\text{V}, \text{V}_{\text{GEN}}=-10\text{V}$ $\text{R}_G=6\Omega, \text{I}_D=1\text{A}$		4	8	nS	
t_r				10	19		
$\text{t}_{\text{d(off)}}$	Turn-Off Time			28.5	42		
t_f				7.6	14		

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.

- A. Surface mounted on FR4 board using 1 in² pad size.
- B. Pulsed width limited by maximum junction temperature, $\text{T}_J(\text{MAX})=150^\circ\text{C}$.
- C. Using $\leq 10\text{s}$ junction-to-ambient thermal resistance is base on $\text{T}_J(\text{MAX})=150^\circ\text{C}$.
- D. Pulse test width $\leq 300\mu\text{s}$ and duty cycle $\leq 2\%$.
- E. Guaranteed by design, not subject to production testing.

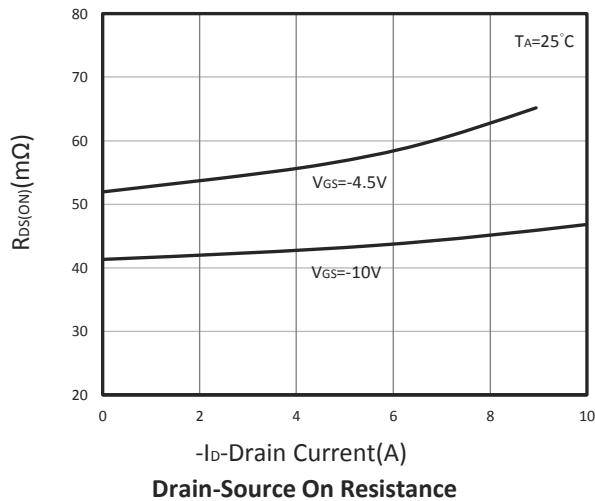
The products and product specifications contained herein are subject to change without notice to improve performance characteristics. Consult us, or our representatives before use, to confirm that the information in this datasheet is up to date. We assume no responsibility for any infringement of patents, patent rights, or other rights arising from the use of any information and circuitry in this datasheet.

TYPICAL CHARACTERISTICS



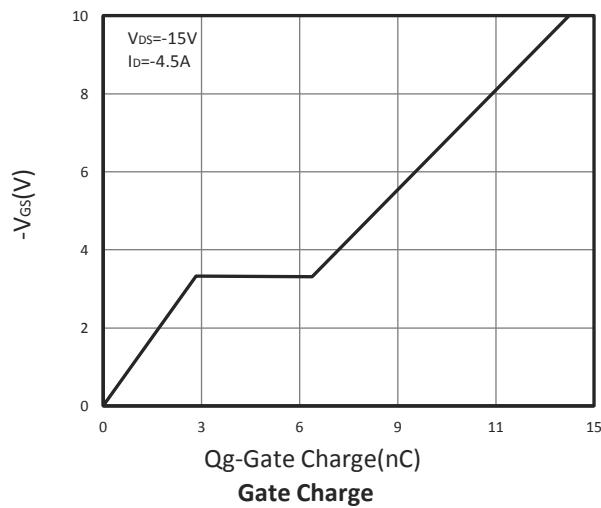
- V_{DS} -Drain Source Voltage(V)

Output Characteristics



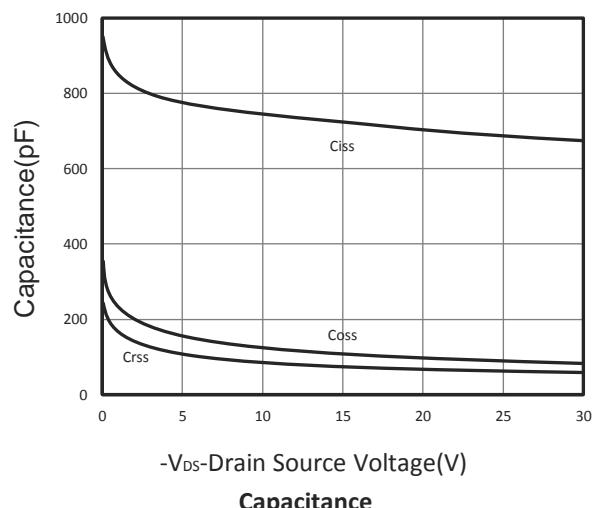
- I_D -Drain Current(A)

Drain-Source On Resistance



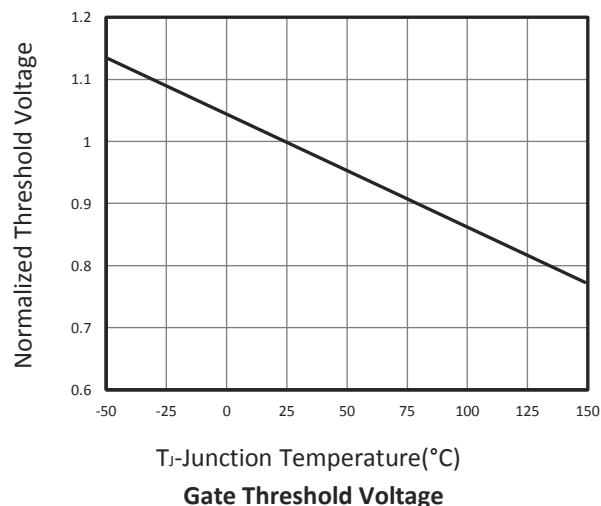
Q_g -Gate Charge(nC)

Gate Charge



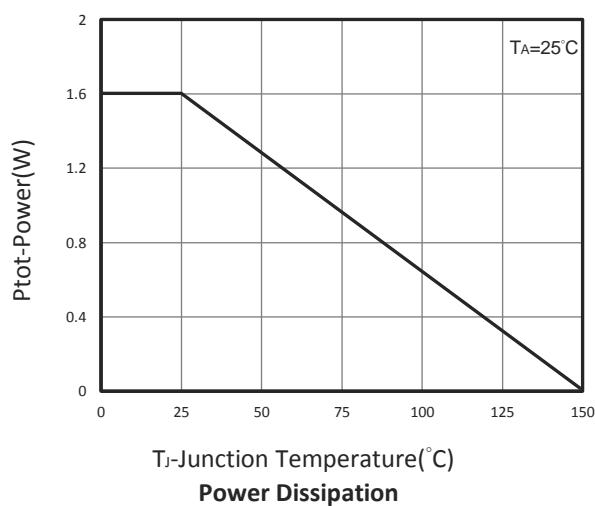
- V_{DS} -Drain Source Voltage(V)

Capacitance



T_j -Junction Temperature(°C)

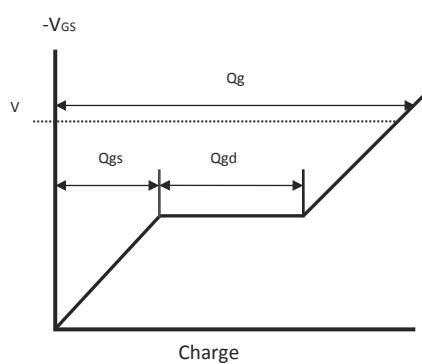
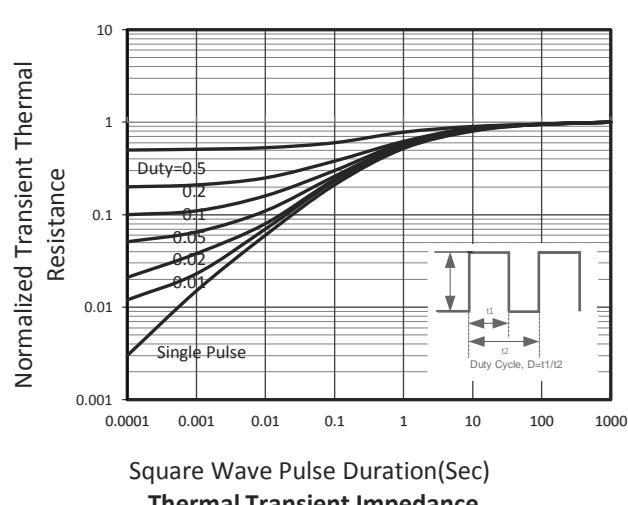
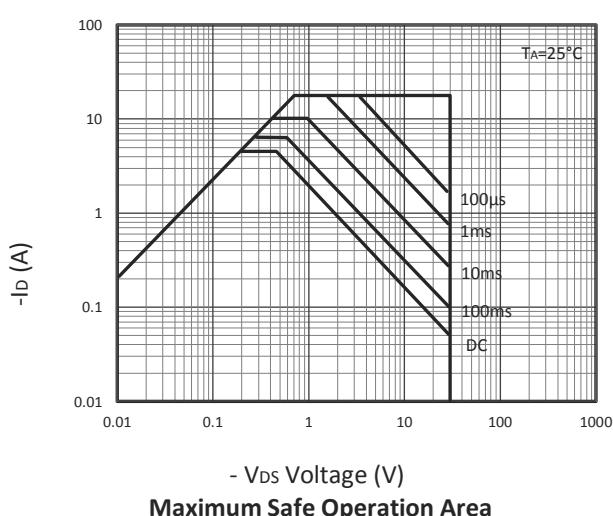
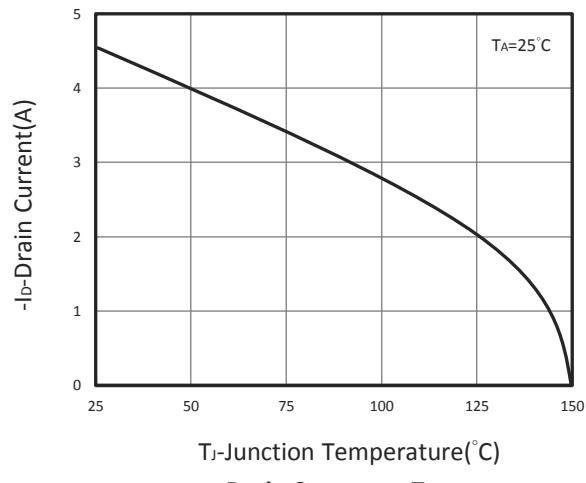
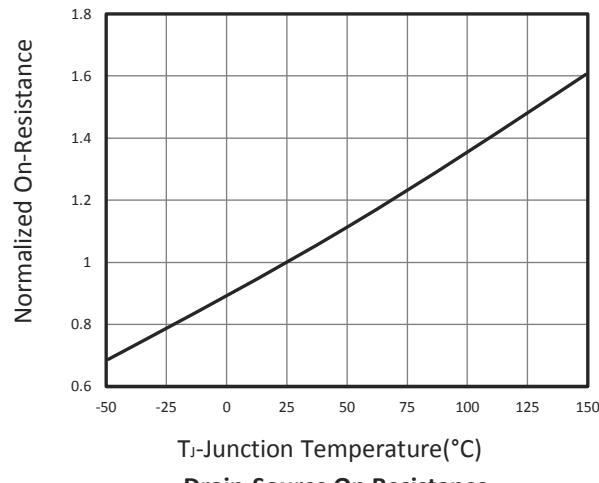
Gate Threshold Voltage



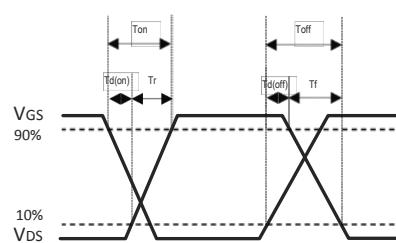
T_j -Junction Temperature(°C)

Power Dissipation

TYPICAL CHARACTERISTICS

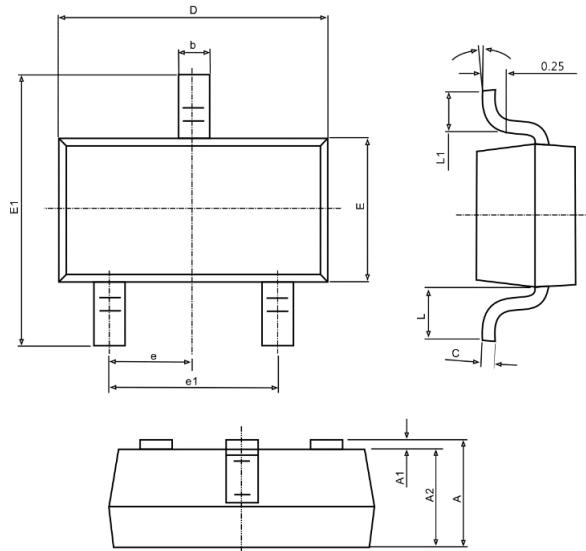


Gate Charge Waveform

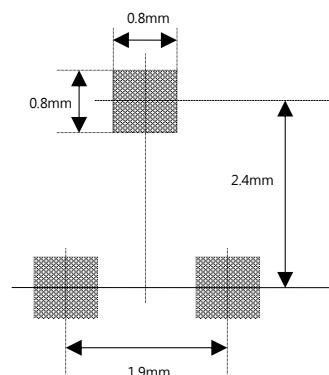


Switching Time Waveform

SOT-23L PACKAGE DIMENSIONS



Recommended Minimum Pad(mm)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.000	1.300	0.039	0.049
A1	0.000	0.100	0.000	0.004
A2	1.000	1.200	0.039	0.047
b	0.300	0.500	0.012	0.020
c	0.047	0.207	0.002	0.008
D	2.800	3.000	0.110	0.118
E	1.500	1.700	0.059	0.067
E1	2.600	3.000	0.102	0.118
e	0.950 TYP.		0.037 TYP.	
e1	1.900 TYP.		0.075 TYP.	
L1	0.250	0.550	0.010	0.022
θ	0°	8°	0°	8°